



DOCUMENT CHANGE REQUEST

DCR number 1369 Changes required for: General

Date: 2021/02/18

Date sent: 2020/01/17

Status: IMPLEMENTED

Originator: Steve Thacker

Organisation: ESCC Executive Secretariat

Title: Integrated Circuits: Monolithic And Multichip Microcircuits, Wire-Bonded, Hermetically Sealed And

Number: 9000

Issue:

10

Other documents affected:

Page:

As applicable

Paragraph:

2.1, 8.1, 8.5, 8.18, 9.5

Original wording:

As per current published specification

Proposed wording:

As part of the ESCC System Improvement Review - Replacing Referenced Test Methods by Suitable Alternatives review, the following ESCC Basic Specifications referenced within ESCC 9000 shall be removed and replaced throughout the specification by the preferred, existing MIL-STD-883 applicable test methods:

Specifications to be removed and replaced are:

- ESCC No. 20400, Internal Visual Inspection: replaced by MIL-STD-883, Test Method 2010, 2013, 2014, 2032 as applicable.
- ESCC No. 20500, External Visual Inspection: replaced by MIL-STD-883, Test Method 2009, 2016 as applicable.
- ESCC No. 21400, Scanning Electron Microscope Inspection: replaced by MIL-STD-883, Test Method 2018.

Justification:

The conclusion of the PSWG task ESCC improvement - ESCC conversion to MIL for Manufacturer STM, as stated in the 84th PSWG MoM, was:

Microchip and STM answer is clear : preference for MIL specifications except for radiation test method.

As the only Manufacturers supporting ESCC 9000 are Microchip & STM, the various referenced ESCC test methods should each be removed and replaced by the appropriate MIL specification test method.

Attachments:

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Modifications:

See DCR 1370 as all discussion of DCR 1369 are included in DCR 1370

Approval signature:



Date signed:

2021-02-18